Vishay Siliconix

COMPLIANT

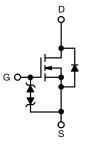
HALOGEN

FREE

E Series Power MOSFET

Thin-Lead TO-220 FULLPAK





N-Channel MOSFET

| PRODUCT SUMMAR | Y | |
|--|-------------------------|------|
| V _{DS} (V) at T _J max. | 85 | 50 |
| R _{DS(on)} typ. (Ω) at 25 °C | $V_{GS} = 10 \text{ V}$ | 1.17 |
| Q _g max. (nC) | 16 | .5 |
| Q _{gs} (nC) | 3 | 3 |
| Q _{gd} (nC) | 6 | 3 |
| Configuration | Sin | gle |

FEATURES

- Low figure-of-merit (FOM) Ron x Qa
- Low effective capacitance (Ciss)
- · Reduced switching and conduction losses
- Ultra low gate charge (Q_a)
- Avalanche energy rated (UIS)
- Integrated Zener diode ESD protection
- · Material categorization: for definitions of compliance please see www.vishay.com/doc?99912

APPLICATIONS

- Server and telecom power supplies
- · Switch mode power supplies (SMPS)
- Power factor correction power supplies (PFC)
- Lighting
 - High-intensity discharge (HID)
 - Fluorescent ballast lighting
- Industrial
 - Welding
 - Induction heating
 - Motor drives
 - Battery chargers
 - Renewable energy

| ORDERING INFORMATION | |
|---------------------------------|--------------------------|
| Package | Thin-Lead TO-220 FULLPAK |
| Lead (Pb)-free and halogen-free | SiHA5N80AE-GE3 |

| PARAMETER | | | SYMBOL | LIMIT | UNIT |
|---|-------------------------|---|-----------------------------------|-------------|--------|
| Drain-source voltage | | | V _{DS} | 800 | |
| Gate-source voltage | | | V_{GS} | ± 30 | - V |
| Continuous drain augreent /T 150 °C\ 6 | V at 10 V | $T_C = 25 ^{\circ}C$ $T_C = 100 ^{\circ}C$ | | 3.0 | |
| Continuous drain current (T _J = 150 °C) ^e | V _{GS} at 10 V | T _C = 100 °C | ID | 1.9 | Α |
| Pulsed drain current ^a | | | I _{DM} | 7 | |
| Linear derating factor | | | | 0.5 | W/°C |
| Single pulse avalanche energy b | | | E _{AS} | 17 | mJ |
| Maximum power dissipation | | | P_{D} | 29 | W |
| Operating junction and storage temperature ra | inge | | T _J , T _{stg} | -55 to +150 | °C |
| Drain-source voltage slope | | T _J = 125 °C | d. //d+ | 70 | 1//20 |
| Reverse diode dv/dt ^d | | | dv/dt | 0.3 | - V/ns |
| Soldering recommendations (peak temperature | e) ^c | For 10 s | | 260 | °C |
| Mounting torque, M3 screw | | • | | 0.6 | Nm |

- a. Repetitive rating; pulse width limited by maximum junction temperature
- b. V_{DD} = 140 V, starting T_J = 25 °C, L = 28.2 mH, R_g = 25 Ω , I_{AS} = 1.1 A
- c. 1.6 mm from case
- d. $I_{SD} \le I_D$, di/dt = 100 A/ μ s, starting $T_{.l}$ = 25 °C
- e. Limited by maximum junction temperature



Vishay Siliconix

| THERMAL RESISTANCE RATI | NGS | | |
|----------------------------------|-------------------|------|------|
| PARAMETER | SYMBOL | MAX. | UNIT |
| Maximum junction-to-ambient | R _{thJA} | 65 | °C/W |
| Maximum junction-to-case (drain) | R _{thJC} | 4.3 | C/VV |

| PARAMETER | SYMBOL | TEST CONDITIONS | | MIN. | TYP. | MAX. | UNIT |
|---|-----------------------|--|--|------|------|------|------|
| Static | | | | | | | • |
| Drain-source breakdown voltage | V _{DS} | V _{GS} = | = 0 V, I _D = 250 μA | 800 | - | - | V |
| V _{DS} temperature coefficient | $\Delta V_{DS}/T_{J}$ | Referenc | Reference to 25 °C, I _D = 1 mA | | 0.8 | - | V/°C |
| Gate-source threshold voltage (N) | V _{GS(th)} | V _{DS} = | V _{GS} , I _D = 250 μA | 2 | - | 4 | V |
| Oala a sandada a | | V _{GS} = ± 20 V | | - | - | ± 10 | |
| Gate-source leakage | I_{GSS} | , | $V_{GS} = \pm 30 \text{ V}$ | - | - | ± 50 | μA |
| Zoro goto voltago drain ourrent | | V _{DS} = 800 V, V _{GS} = 0 V | | - | - | 1 | |
| Zero gate voltage drain current | I _{DSS} | V _{DS} = 640 V | , V _{GS} = 0 V, T _J = 125 °C | - | - | 10 | μA |
| Drain-source on-state resistance | R _{DS(on)} | V _{GS} = 10 V | I _D = 1.5 A | - | 1.17 | 1.35 | Ω |
| Forward transconductance ^a | 9 _{fs} | V _{DS} = 30 V, I _D = 2 A | | - | 1.2 | - | S |
| Dynamic | | | | | | | |
| Input capacitance | C _{iss} | $V_{GS} = 0 V$, | | - | 321 | - | pF |
| Output capacitance | C _{oss} | Ţ, | $V_{DS} = 100 V$, | | 20 | - | |
| Reverse transfer capacitance | C _{rss} | f = 1 MHz | | - | 4 | - | |
| Effective output capacitance, energy related ^a | C _{o(er)} | | | - | 14 | - | |
| Effective output capacitance, time related ^b | C _{o(tr)} | V _{DS} = 0 V | $V_{DS} = 0 \text{ V to } 480 \text{ V}, V_{GS} = 0 \text{ V}$ | | 71 | - | |
| Total gate charge | Qg | | | - | 11 | 16.5 | |
| Gate-source charge | Q _{gs} | V _{GS} = 10 V | $I_D = 2 A, V_{DS} = 640 V$ | - | 3 | - | nC |
| Gate-drain charge | Q _{gd} | | | - | 6 | - | |
| Turn-on delay time | t _{d(on)} | V _{DD} = 640 V, I _D = 2 A, | | - | 12 | 24 | ns |
| Rise time | t _r | | | - | 8 | 16 | |
| Turn-off delay time | t _{d(off)} | V _{GS} = | $V_{GS} = 10 \text{ V}, R_g = 9.1 \Omega$ | | 10 | 20 | |
| Fall time | t _f | 1 | | - | 28 | 56 | |
| Gate input resistance | R_g | f = 1 MHz, open drain | | 1.6 | 3.2 | 6.4 | Ω |
| Drain-Source Body Diode Characteristic | s | | | | | | |
| Continuous source-drain diode current | I _S | MOSFET symbol showing the integral reverse p - n junction diode | | - | - | 4.4 | |
| Pulsed diode forward current | I _{SM} | | | - | - | 7 | - A |
| Diode forward voltage | V _{SD} | T _J = 25 °C, I _S = 2 A, V _{GS} = 0 V | | - | - | 1.2 | V |
| Reverse recovery time | t _{rr} | - | | - | 267 | 534 | ns |
| Reverse recovery charge | Q _{rr} | $T_J = 25 \text{ °C, } I_F = I_S = 2 \text{ A,}$ $di/dt = 100 \text{ A/}\mu\text{s, } V_R = 25 \text{ V}$ | | - | 1.2 | 2.4 | μC |
| Reverse recovery current | I _{RRM} | | | _ | 7.5 | - | A |

Notes

- a. $C_{oss(er)}$ is a fixed capacitance that gives the same energy as C_{oss} while V_{DS} is rising from 0 V to 480 V V_{DSS}
- b. $C_{oss(tr)}$ is a fixed capacitance that gives the same charging time as C_{oss} while V_{DS} is rising from 0 V to 480 V V_{DSS}



TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

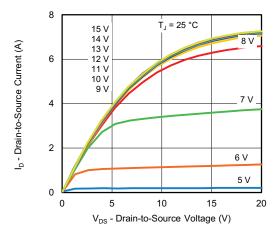


Fig. 1 - Typical Output Characteristics

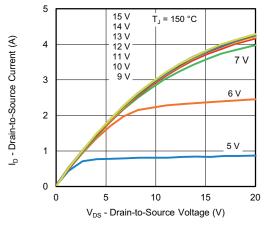


Fig. 2 - Typical Output Characteristics

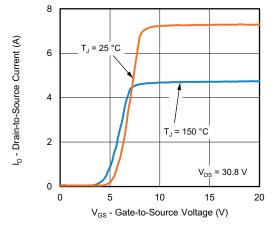


Fig. 3 - Typical Transfer Characteristics

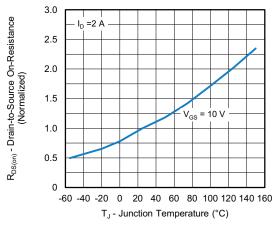


Fig. 4 - Normalized On-Resistance vs. Temperature

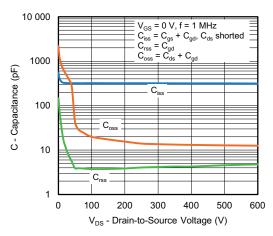


Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage

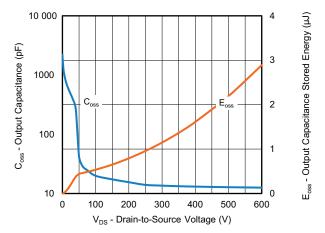


Fig. 6 - Coss and Eoss vs. VDS



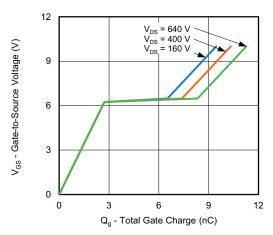


Fig. 7 - Typical Gate Charge vs. Gate-to-Source Voltage

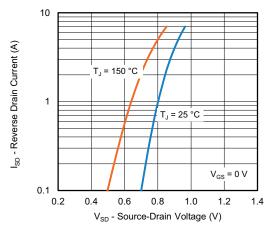


Fig. 8 - Typical Source-Drain Diode Forward Voltage

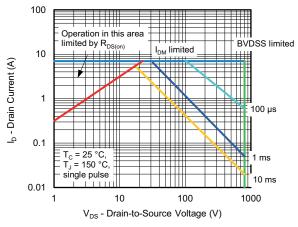


Fig. 9 - Maximum Safe Operating Area



a. V_{GS} > minimum V_{GS} at which $R_{DS(on)}$ is specified

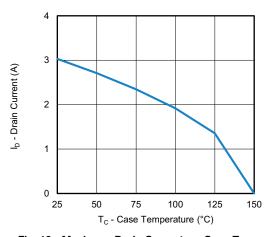


Fig. 10 - Maximum Drain Current vs. Case Temperature

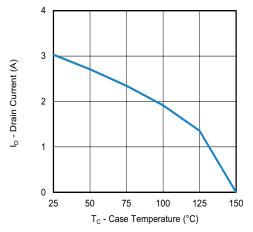


Fig. 11 - Normalized Breakdown Voltage vs. Temperature



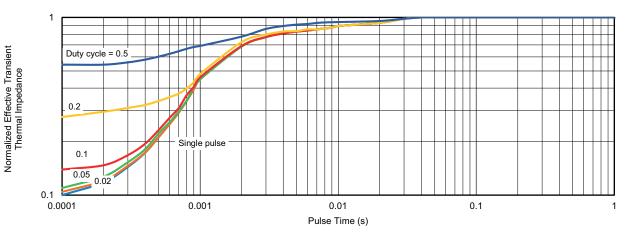


Fig. 12 - Normalized Transient Thermal Impedance, Junction-to-Case

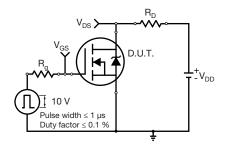


Fig. 13 - Switching Time Test Circuit

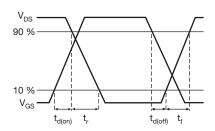


Fig. 14 - Switching Time Waveforms

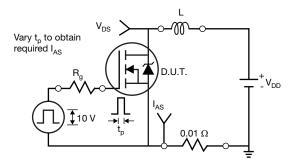


Fig. 15 - Unclamped Inductive Test Circuit

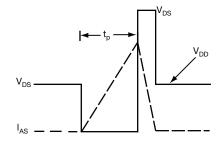


Fig. 16 - Unclamped Inductive Waveforms

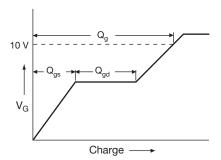


Fig. 17 - Basic Gate Charge Waveform

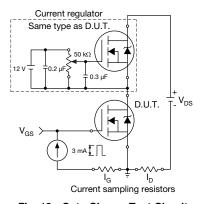


Fig. 18 - Gate Charge Test Circuit



Peak Diode Recovery dv/dt Test Circuit

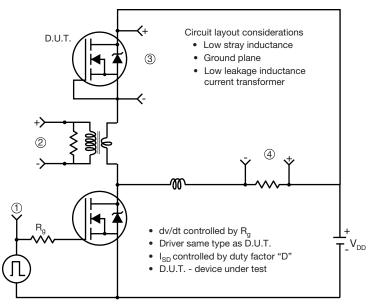




Fig. 19 - For N-Channel

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TO-220 FULLPAK Thin Lead





| SYMBOL | DIMENSIONS | | | | |
|--------|------------|--------|--------|-------|--|
| | MILLIN | IETERS | INCHES | | |
| | MIN. | MAX. | MIN. | MAX. | |
| Α | 4.30 | 4.70 | 0.169 | 0.185 | |
| A1 | 2.50 | 2.90 | 0.098 | 0.114 | |
| A2 | 2.40 | 2.80 | 0.094 | 0.110 | |
| b | 0.60 | 0.80 | 0.024 | 0.031 | |
| b2 | 0.60 | 0.90 | 0.024 | 0.035 | |
| С | = | 0.60 | - | 0.024 | |
| D | 8.30 | 8.70 | 0.327 | 0.342 | |
| d1 | 14.70 | 15.30 | 0.579 | 0.602 | |
| d2 | 2.90 | 3.10 | 0.114 | 0.122 | |
| d3 | 3.30 | 3.70 | 0.130 | 0.146 | |
| Е | 9.70 | 10.30 | 0.382 | 0.406 | |
| е | 2.50 | 2.70 | 0.098 | 0.106 | |
| L | 13.40 | 13.80 | 0.528 | 0.543 | |
| L1 | 1.00 | 2.80 | 0.039 | 0.110 | |
| ØP | 3.00 | 3.40 | 0.118 | 0.134 | |

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DWG: 6021



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